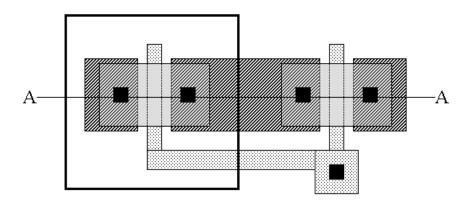


EECS 105 – Microelectronic Devices and Circuits Spring 2001, Prof. A. R. Neureuther Dept. EECS, 510 Cory 642-4590 UC Berkeley Tentative OH M11, (Tu2), W2, Th2, F11 Course Web Site http://www-inst.EECS.Berkeley.EDU/~ee105/

Homework Assignment # 2, Due February 2, 2001

All circuits in the following problems are fabricated in a N-well CMOS process

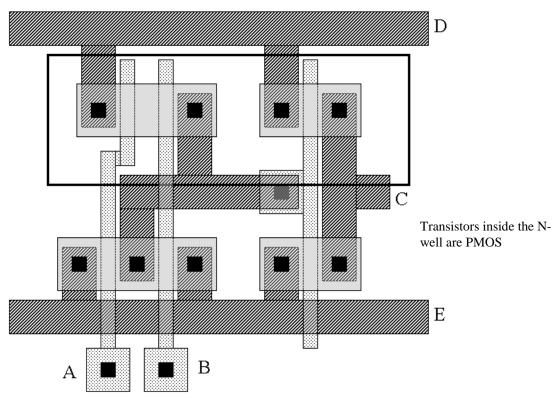
- oxide mask (dark field)
- polysilicon mask (clear field)
- contact mask (dark field)
- metal mask (clear field)
- N-well mask (dark field)
- **2.1 CMOS process flow.** Consider the layout of a CMOS inverter. Use the 6 step process flow in Chapter 2 and add one additional mask (N-well) and two additional steps (N-well implant prior to step 1 and P-type source/drain implant prior to step 5.



a) Draw the cross section at cut-line A-A immediately after polysilicon etching

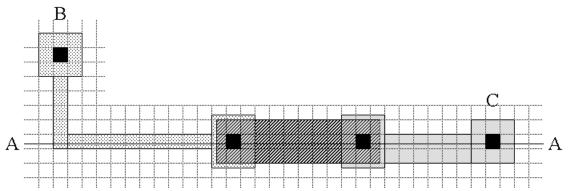
b) Draw the cross section at cut-line A-A immediately after contact opening Specify substrate type, doping types in source/drain areas and each layer in your schematic.

2.2 CMOS Circuit. Consider the layout of a CMOS circuit



Draw the circuit diagram (show all wirings and MOSFETs)

2.3 IC resistors. Consider the layout of an IC resistor. Assume sheet resistances of N+ doping, polysilicon and metal are 100Ω /square, 10Ω /square and 0.01Ω /square, respectively.



- a) Sketch the cross section of the resistor at cut-line A-A
- b) Calculate the total resistance R_{BC} (Contact and corner resistances should be considered in your calculation. Assume that the contact regions each contribute 0.65 squares)

2.4 IC resistors.

- a) If the N+ doping in problem 2.3 is 0.5um deep and the distribution of dopant is uniform, find the doping concentration. (Assume the grid show on the drawing have 0.5um openings)
- b) A $10k\Omega$ resistor R₁ and a $5k\Omega$ resistor R₂ combines in series so that their resistances add. If R₁ has an uncertainty of 500Ω and the uncertainty in R₂ is 400Ω . What is the uncertainty in R₁+R₂?